

ELECTROPLATING METHOD AND ELECTROPLATING APPARATUS

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Abstract of JP2002220690

PROBLEM TO BE SOLVED: To provide an electroplating method which forms a metal plated layer such as gold and silver, so as to have a requested film-thickness distribution on the surface of a material to be plated, and an electroplating apparatus used in the method.

SOLUTION: This method comprises passing a plating solution of silver cyanide, from several feed openings of the plating solution at the bottom of the cell, upward into the cell in which the material to be plated is vertically arranged as a cathode so as to face an anode. Then, it comprises decreasing a flow velocity of the plating solution in the space which is formed between the surface on which the plating thickness is controlled, out of both surfaces of the material to be plated as the cathode, and the anode facing to it, by arranging a jig so as to block the lower feed openings in the space for the plating solution; electrifying; and electroplating to form a silver plating layer having the requested film thickness distribution.

